

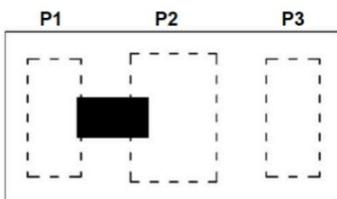
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

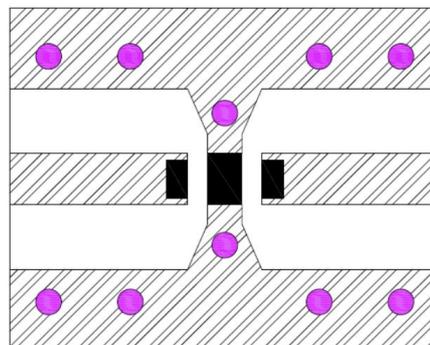
NO.	Parameter	Frequency (MHz)	SPC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)	3300~4200			1.7
2	VSWR				2.0
3	Attenuation (dB)	100~2570	35		
		2170	40		
		2620~2690	25		
		5150~5950	20		
		6600~8400	27		
4	In/Output Impedance (Ω)		50		
5	Permissible Input Power (W)				3
Operating & Storage Condition (Component) Operation Temperature Range: -40°C ~ +85°C Storage Temperature Range: -40°C ~ +85°C					
Storage Condition before Soldering (Included packaging material) Storage Temperature Range: +5 ~ +40 °C Humidity: 30 to 70% relative humidity					

Construction



PIN	Connection
1	Input port
2	GND
3	Output port

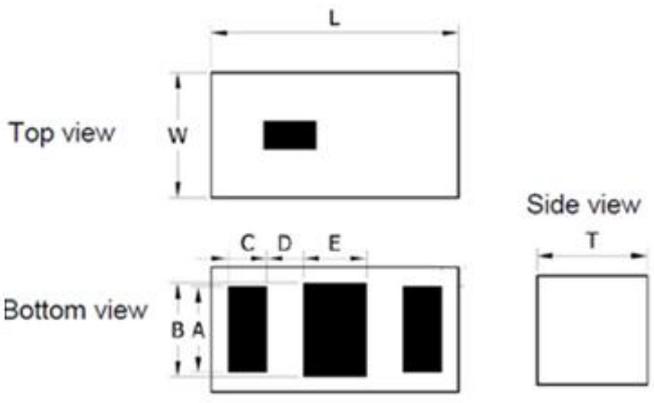
Mounting Considerations



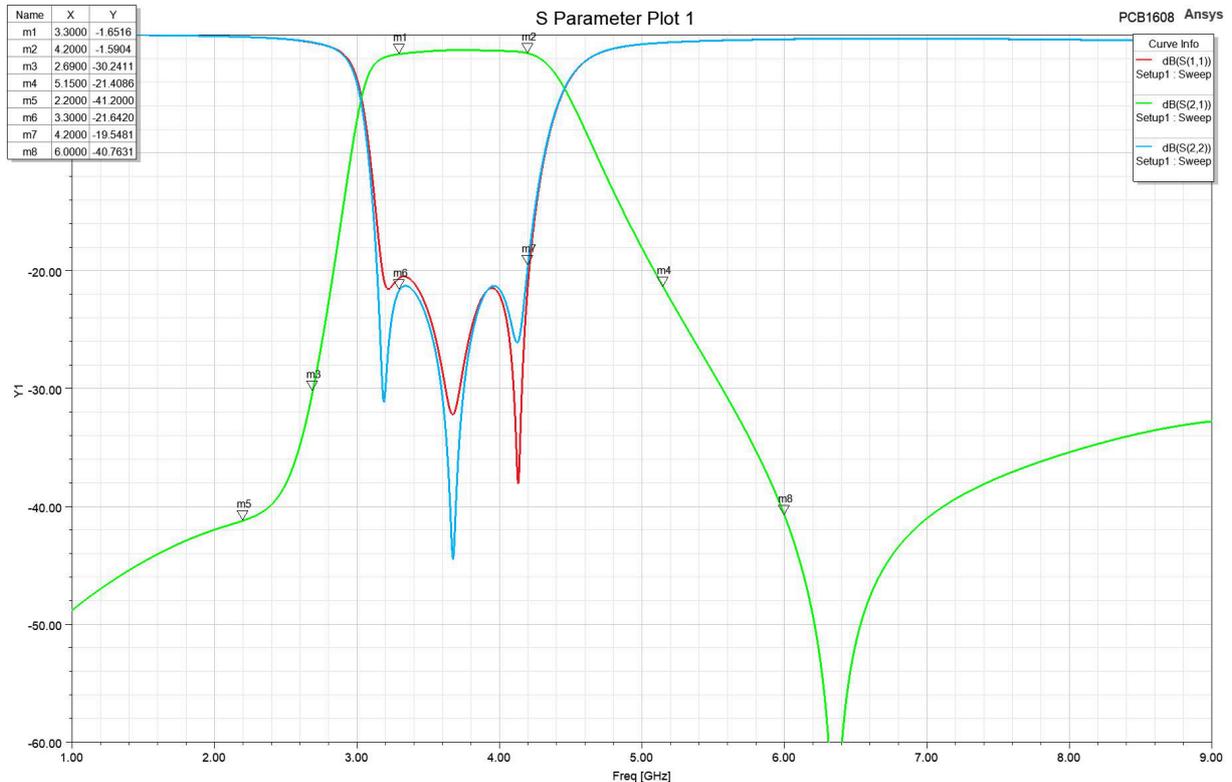
- Land
- ▨ Solder
- Through-hole

Unit: mm
 Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
	L	1.60±0.10
	W	0.80±0.10
	T	0.60±0.10
	A	0.70±0.10
	B	0.70±0.10
	C	0.30±0.10
	D	0.25±0.10
E	0.40±0.10	

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.